MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

WLCSP30 2.38x1.98x0.586
CASE 567SR
ISSUE O

DATE 30 NOV 2016

TOP VIEW

LAND PATTERN RECOMMENDATION
(NSMD PAD TYPE)

SIDE VIEWS

BOTTOM VIEW

NOTES:
A. NO JEDEC REGISTRATION APPLIES.
B. DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS AND TOLERANCE
D. DATUM C IS DEFINED BY THE SPHERICAL
CROWNS OF THE BALLS.
E. PACKAGE NOMINAL HEIGHT IS 586 MICRONS
(±39 MICRONS (547-625 MICRONS).
F. FOR DIMENSIONS D, E, X, AND Y SEE
PRODUCT DatasHEET.

DOCUMENT NUMBER: 98AON16615G
STATUS: ON SEMICONDUCTOR STANDARD

NEW STANDARD:
DESCRIPTION: WLCSP30 2.38x1.98x0.586

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PAGE 1 OF 2
<table>
<thead>
<tr>
<th>ISSUE</th>
<th>REVISION</th>
<th>DATE</th>
</tr>
</thead>
<tbody>
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<td>RELEASED FOR PRODUCTION FROM FAIRCHILD UC030AB TO ON SEMICONDUCTOR,REQ. BY F. ESTRADA.</td>
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